one up – A New Dimension of Dispensing: Scheugenpflug System Solutions
What can our modular system offer you?

- High flexibility and scalability
- Short delivery times
- High quality of the individual modules
- High future viability

Flexibility is Our Standard

The modular system concept from Scheugenpflug

In the case of dispensing systems there are hardly any “complete off-the-shelf solutions”. Rather, the systems must be selected for compatibility with the workpiece and the adhesive, sealant or potting material used. Even factors such as the specific dispensing task, the required cycle time as well as quality requirements and the process environment play an important role in designing the optimal dispensing system. The conflict of interest between superior performance and cost must therefore be solved differently. We solve this problem with modularity.

The basis for your optimal system solution is our modular system consisting of standardized modules. Individual processes can be taken from the modular system and combined according to your individual requirements – while maintaining the standard. For instance our dispensing cell concept, which is based on many different material preparation and feeding units, dispensers, axis systems, operating concepts and control units in scalable enclosures, provides the best fit at series production prices. The same approach is used for manual work stations and is linked to the production environment when using special integration systems.

If your production changes, our systems flexibly change with it. The systems can handle it all: different materials, larger production quantities, faster cycle times, higher quality requirements, more process reliability, etc. You define what you need and we configure the best system for you. Further enhancements are continually incorporated in our solutions. You decide the point at which adding an extension is worthwhile to you. However, with each modification of your modules, they will remain “state of the art”. 

Adhesive bonding

In this process, sensitive electronic surfaces are coated with a very thin layer of potting resin or protective varnish. For effective protection, it is essential to thoroughly coat the surface, including electrical contacts, soldered connections and other surface structures. Low-viscosity potting materials are therefore used in this process.

Potting

Depending on the geometry of the component or the properties of the potting material, the filling process must be carried out in different ways. The medium can be potted in one go, simultaneously at several points or with interruptions. A further variant is the “Dam and Fill” or “Frame and Fill”, in which a sealing bead (the dam or frame) is applied as a contour first and the inner area is then filled with another potting material.

Sealing

In this process, sensitive electronic surfaces are coated with a very thin layer of potting resin or protective varnish. For effective protection, it is essential to thoroughly coat the surface, including electrical contacts, soldered connections and other surface structures. Low-viscosity potting materials are therefore used in this process.
Let's talk about your project:
+49 9445 9564 ext. 0, vertrieb.de@scheugenpflug.de

With our high-performance system solution for self-leveling media, you can take your dispensing process to a new level!

### Task
- Material and material properties
- Material preparation and feeding with the LiquiPrep LP804
- Material application with the dispenser DosP DP803
- Process automation with the DispensingCell DC803
- High-performance system solution

### LiquiPrep LP804
**Top material quality - the basis for optimum dispensing results**
- Absolutely homogeneous and bubble-free potting material in a short time
- Long service life thanks to intelligent diaphragm feed pump
- Constantly high feeding performance
- Convenient operation and maintenance

**UVIS control unit:** Optimal visualization of the dispensing process
- Easily handle various dispensing programs
- Customizable overview of system and process parameters
- Extensive permission management

**Info:** Learn more about the UVIS
www.scheugenpflug.de/en/uvis-upic

### EViS control unit:
**Focus on usability**
- Intuitive operation
- Fast activation of functions
- Easy adaptation of process parameters

**Info:** Learn more about the EViS
www.scheugenpflug.de/en/evis

### Piston dispenser: DosP DP803:
**High-precision material application, robust construction**
- All-round solution for the most varied materials and dispensing tasks
- Highest precision and process reliability
- 30% more compact design, more than 15% lighter
- Market leading service life

### DispensingCell DC803:
**High-performance multifunctional cell**
- Highest performance for series production
- Flexible configuration and high scalability
- High usability thanks to intelligent machine control unit
- Extensive options for process monitoring

### Competitiveness is a challenge for companies in dynamic times. The challenge is to react quickly, flexibly and economically to changing customer requirements. Our scalable system solutions will help you.

In order to achieve optimum results, it is important to take a comprehensive approach to the dispensing process. Based on your task and the material to be processed, we select the right components from our modular system and combine them to form a precisely fitting system solution. Material preparation, feeding and dispensing as well as process automation are optimally coordinated here.

Our new, high-performance system solution for self-leveling media offers you maximum quality and flexibiility for your dispensing application. In addition to using it as a stand-alone system, its software can also be integrated directly into existing production environments.

Thanks to various equipment options and additional functionalities, you have even more options to adapt the process to your needs. Of course, you can take top dispensing results for granted.

- Absolutely homogeneous and bubble-free potting material in a short time
- Long service life thanks to intelligent diaphragm feed pump
- Consistently high feeding performance
- Convenient operation and maintenance

**LiquiPrep LP804:**
Top material quality – the basis for optimum dispensing results

**UVIS5 control unit:**
Optimal visualization of the dispensing process

**EViS control unit:**
Focus on usability

**Piston dispenser: DosP DP803:**
High-precision material application, robust construction

**DispensingCell DC803:**
High-performance multifunctional cell

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PRE-LAUNCH
Contact our sales team for further information!
Perfect for your application

With our new system solution, numerous different dispensing tasks can be realized – individually tailored to your requirements and in top quality.

**Adhesive bonding**

The complexity of adhesive bonding processes is often underestimated. To make sure that effective, lasting adhesive bonds can be achieved, the upstream and downstream process steps also need to be taken into account in addition to material application and the subsequent joining process only. Hybrid processes, in which bonding is supplemented by a further function such as sealing or heat dissipation, are becoming increasingly important.

Info: Learn more about adhesive bonding
www.scheugenpflug.de/en/adhesive-bonding

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Info: Learn more about potting
www.scheugenpflug.de/en/potting

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Info: Learn more about sealing
www.scheugenpflug.de/en/conformal-coating